RENESAS

Product Change Notification

(Notification - P1602009-DIGI)

(CST-R2-T672)

March 15, 2016

To: *Our Valued Digi-Key, Inc. Customer*

Overview: The purpose of this notification is to communicate a product change for select Renesas Electronics America, Inc. (REA) devices. These devices have replacement part numbers.

This notification announces the change assembly and final test sites for certain 4Mb Low Power SRAM TSOP products. The table below describes the site changes.

	Current Site	New Site
Assembly Site	Renesas Semiconductor Beijing	Amkor Technology Malaysia
Final Test Site	Renesas Semiconductor Beijing	Powertech Technology Inc.

There are **no changes** to the wafer fabrication site, electrical characteristics (DC/AC), package materials, package dimensions, pin configurations, or product reliability & quality.

There are some changes to the packing specification. See the Appendix for details.

Affected Products: A review of our shipment records to your company indicate the attached list of products is affected by this notification.

Booking Part Number	Replacement Part Number
RMLV0408EGSB-4S2#AA**0**	RMLV0408EGSB-4S2#AA**1**
RMLV0408EGSB-4S2#HA**0**	RMLV0408EGSB-4S2#HA**1**
RMLV0414EGSB-4S2#AA**0**	RMLV0414EGSB-4S2#AA**1**
RMLV0414EGSB-4S2#HA**0**	RMLV0414EGSB-4S2#HA**1**
RMLV0416EGSB-4S2#AA**0**	RMLV0416EGSB-4S2#AA**1**
RMLV0416EGSB-4S2#HA**0**	RMLV0416EGSB-4S2#HA**1**

Part numbers given in this list are for active part numbers in REA database at the time of this notification.

Key Dates:

Mass production shipments of the **replacement part number** begin from REA.	**Jun. 15th, 2016**

Response: No response is required. REA will consider this notification approved 30 days after its issue. If you anticipate volumes beyond your regular rate prior to the transition date, please contact your REA sales representative with a forecast of your requirements.

You are encouraged to sample the replacement device and begin qualification as soon as possible. Please contact you REA sales representative to obtain samples.

Please contact your REA sales representative for any questions or comments.

Thank you for your attention.

Sincerely,

Renesas Electronics America, Inc.

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Appendix A: RMLV0408EGSB-4S2 Comparison Table (32pin TSOP (II) package)

Item		Current	After	Remarks
Orderable part number		RMLV0408EGSB-4S2#AA0 (Tray packing) RMLV0408EGSB-4S2#HA0 (Tape & Reel packing)	RMLV0408EGSB-4S2#AA1 (Tran packing) RMLV0408EGSB-4S2#HA1 (Tape & Reel packing)	
Assembly Line		Renesas Semiconductor Beijing (China)	Amkor Technology Malaysia (Malaysia)	
Country of origin display		CHINA	MALAYSIA	
JEITA Package Code		P-TSOP(2)32-10.16x20.95-1.27	P-TSOP(2)32-10.16x20.95-1.27	compatible mounting
Package Marking Specification		Country of origin (Back-End Line: Assembly) RMLV0408EGSB → Part name CHINA 4S2 → Electrical characteristics XXXXXXX → Date Code	Country of origin (Back-End Line: Assembly) RMLV0408EGSB → Part name MALAYSIA 4S2 → Electrical characteristics XXXXXXX → Date Code	
Material	Lead frame material	Cu	Cu	material is equivalent
	Lead frame pattern	Current specification	New specification(change in pattern)	
	Lead plating	Pure Tin	Pure Tin	material is equivalent
	Die bonding	Epoxy paste	Epoxy paste	material is equivalent
	Wire bonding	Au	Au	material is equivalent
	Mold	Epoxy resin	Epoxy resin	material is equivalent
Final test Line		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)	
Tray packing	Packing Specification	Current specification	New specification	
	Tray	JEDEC Tray (TSOP II package size: 10.16mm x 20.95mm)	JEDEC Tray (TSOP II package size: 10.16mm x 20.95mm)	material is equivalent
	Storage number	117pcs/tray	117pcs/tray	
	Number of trays(Max.)	8 trays + 1 tray(cover)	10 trays + 1 tray(cover)	
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm	
Tape & Reel packing	Packing Specification	Current specification	New specification	
	Embossed tape	Current specification	New specification	No change in dimension
	Storage number	1,000pcs/reel	1,000pcs/reel	
	Inner box size (LxWxH)	288mm x 273mm x 48mm	340mm x 360mm x 60mm	
Shipping label		Current specification	No change in specification	Changes in orderable part name and country of origin

Appendix B: RMLV0416EGSB-4S2 Comparison Table (44pin TSOP (II) package)

Item		Current	After	Remarks
Orderable part number		RMLV0416EGSB-4S2#AA0 (Tray packing) RMLV0416EGSB-4S2#HA0 (Tape & Reel packing)	RMLV0416EGSB-4S2#AA1 (Tray packing) RMLV0416EGSB-4S2#HA1 (Tape & Reel packing)	
Assembly Line		Renesas Semiconductor Beijing (China)	Amkor Technology Malaysia (Malaysia)	
Country of origin display		CHINA	MALAYSIA	
JEITA Package Code		P-TSOP(2)44-10.16x18.41-0.80	P-TSOP(2)44-10.16x18.41-0.80	compatible mounting
Package Marking Specification		Country of origin (Back-End Line: Assembly) RMLV0416EGSB → Part name CHINA 4S2 → Electrical characteristics XXXXXXX → Date Code	Country of origin (Back-End Line: Assembly) RMLV0416EGSB → Part name MALAYSIA 4S2 → Electrical characteristics XXXXXXX → Date Code 1pin mark	
Material	Lead frame material	Cu	Cu	material is equivalent
	Lead frame pattern	Current specification	New specification(change in pattern)	
	Lead plating	Pure Tin	Pure Tin	material is equivalent
	Die bonding	Epoxy paste	Epoxy paste	material is equivalent
	Wire bonding	Au	Au	material is equivalent
	Mold	Epoxy resin	Epoxy resin	material is equivalent
Final test Line		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)	
Tray packing	Packing Specification	Current specification	New specification	
	Tray	JEDEC Tray (TSOP II package size: 10.16mm x 18.41mm)	JEDEC Tray (TSOP II package size: 10.16mm x 18.41mm)	material is equivalent
	Storage number	135pcs/tray	135pcs/tray	
	Number of trays(Max.)	8 trays + 1 tray(cover)	10 trays + 1 tray(cover)	
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm	
Tape & Reel packing	Packing Specification	Current specification	New specification	
	Embossed tape	Current specification	New specification	No change in dimension
	Storage number	1,000pcs/reel	1,000pcs/reel	
	Inner box size (LxWxH)	288mm x 273mm x 48mm	340mm x 360mm x 60mm	
Shipping label		Current specification	No change in specification	Changes in orderable part name and country of origin

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Appendix C: RMLV0414EGSB-4S2, Chip-select terminal: 1-pin type Comparison Table (44pin TSOP (II) package)

Item		Current	After	Remarks
Orderable part number		RMLV0414EGSB-4S2#AA0 (Tray packing) RMLV0414EGSB-4S2#HA0 (Tape & Reel packing)	RMLV0414EGSB-4S2#AA1 (Tray packing) RMLV0414EGSB-4S2#HA1 (Tape & Reel packing)	
Assembly Line		Renesas Semiconductor Beijing (China)	Amkor Technology Malaysia (Malaysia)	
Country of origin display		CHINA	MALAYSIA	
JEITA Package Code		P-TSOP(2)44-10.16x18.41-0.80	P-TSOP(2)44-10.16x18.41-0.80	compatible mounting
Package Marking Specification		RMLV0414EGSB → Part name CHINA 4S2 → Electrical characteristics XXXXXXX → Date Code Country of origin (Back-End Line: Assembly)	RMLV0414EGSB → Part name MALAYSIA 4S2 → Electrical characteristics XXXXXXX → Date Code Country of origin (Back-End Line: Assembly) 1pin mark	
Material	Lead frame material	Cu	Cu	material is equivalent
	Lead frame pattern	Current specification	New specification(change in pattern)	
	Lead plating	Pure Tin	Pure Tin	material is equivalent
	Die bonding	Epoxy paste	Epoxy paste	material is equivalent
	Wire bonding	Au	Au	material is equivalent
	Mold	Epoxy resin	Epoxy resin	material is equivalent
Final test Line		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)	
Tray packing	Packing Specification	Current specification	New specification	
	Tray	JEDEC Tray (TSOP II package size: 10.16mm x 18.41mm)	JEDEC Tray (TSOP II package size: 10.16mm x 18.41mm)	material is equivalent
	Storage number	135pcs/tray	135pcs/tray	
	Number of trays(Max.)	8 trays + 1 tray(cover)	10 trays + 1 tray(cover)	
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm	
Tape & Reel packing	Packing Specification	Current specification	New specification	
	Embossed tape	Current specification	New specification	No change in dimension
	Storage number	1,000pcs/reel	1,000pcs/reel	
	Inner box size (LxWxH)	288mm x 273mm x 48mm	340mm x 360mm x 60mm	
Shipping label		Current specification	No change in specification	Changes in orderable part name and country of origin